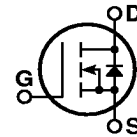


POWER MOS V™

Power MOS V™ is a new generation of high voltage N-Channel enhancement mode power MOSFETs. This new technology minimizes the JFET effect, increases packing density and reduces the on-resistance. Power MOS V™ also achieves faster switching speeds through optimized gate layout.



- **Faster Switching**
- **100% Avalanche Tested**
- **Lower Leakage**
- **Surface Mount D³PAK Package**



MAXIMUM RATINGS

All Ratings: $T_C = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	APT6040SVR	UNIT
V_{DSS}	Drain-Source Voltage	600	Volts
I_D	Continuous Drain Current @ $T_C = 25^\circ\text{C}$	16	Amps
I_{DM}	Pulsed Drain Current ①	64	
V_{GS}	Gate-Source Voltage Continuous	± 30	Volts
V_{GSM}	Gate-Source Voltage Transient	± 40	
P_D	Total Power Dissipation @ $T_C = 25^\circ\text{C}$	250	Watts
	Linear Derating Factor	2	W/°C
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to 150	°C
T_L	Lead Temperature: 0.063" from Case for 10 Sec.	300	
I_{AR}	Avalanche Current ① (Repetitive and Non-Repetitive)	16	Amps
E_{AR}	Repetitive Avalanche Energy ①	30	mJ
E_{AS}	Single Pulse Avalanche Energy ④	960	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-Source Breakdown Voltage ($V_{GS} = 0V, I_D = 250\mu A$)	600			Volts
$I_{D(on)}$	On State Drain Current ② ($V_{DS} > I_{D(on)} \times R_{DS(on)}$ Max, $V_{GS} = 10V$)	16			Amps
$R_{DS(on)}$	Drain-Source On-State Resistance ② ($V_{GS} = 10V, 0.5 I_{D[Cont.]}$)			0.40	Ohms
I_{DSS}	Zero Gate Voltage Drain Current ($V_{DS} = V_{DSS}, V_{GS} = 0V$)			25	μA
	Zero Gate Voltage Drain Current ($V_{DS} = 0.8 V_{DSS}, V_{GS} = 0V, T_C = 125^\circ\text{C}$)			250	
I_{GSS}	Gate-Source Leakage Current ($V_{GS} = \pm 30V, V_{DS} = 0V$)			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage ($V_{DS} = V_{GS}, I_D = 1.0mA$)	2		4	Volts



CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

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DYNAMIC CHARACTERISTICS

APT6040SVR

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C _{iss}	Input Capacitance	V _{GS} = 0V V _{DS} = 25V f = 1 MHz		2600		pF
C _{oss}	Output Capacitance			315		
C _{rss}	Reverse Transfer Capacitance			115		
Q _g	Total Gate Charge ③	V _{GS} = 10V V _{DD} = 0.5 V _{DSS} I _D = I _{D[Cont.]} @ 25°C		115		nC
Q _{gs}	Gate-Source Charge			11		
Q _{gd}	Gate-Drain ("Miller") Charge			46		
t _{d(on)}	Turn-on Delay Time	V _{GS} = 15V V _{DD} = 0.5 V _{DSS} I _D = I _{D[Cont.]} @ 25°C R _G = 1.6Ω		14		ns
t _r	Rise Time			14		
t _{d(off)}	Turn-off Delay Time			47		
t _f	Fall Time			7		

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
I _S	Continuous Source Current (Body Diode)			16	Amps
I _{SM}	Pulsed Source Current ① (Body Diode)			64	
V _{SD}	Diode Forward Voltage ② (V _{GS} = 0V, I _S = -I _{D[Cont.]})			1.3	Volts
t _{rr}	Reverse Recovery Time (I _S = -I _{D[Cont.]} , di _S /dt = 100A/μs)		370		ns
Q _{rr}	Reverse Recovery Charge (I _S = -I _{D[Cont.]} , di _S /dt = 100A/μs)		5.2		μC

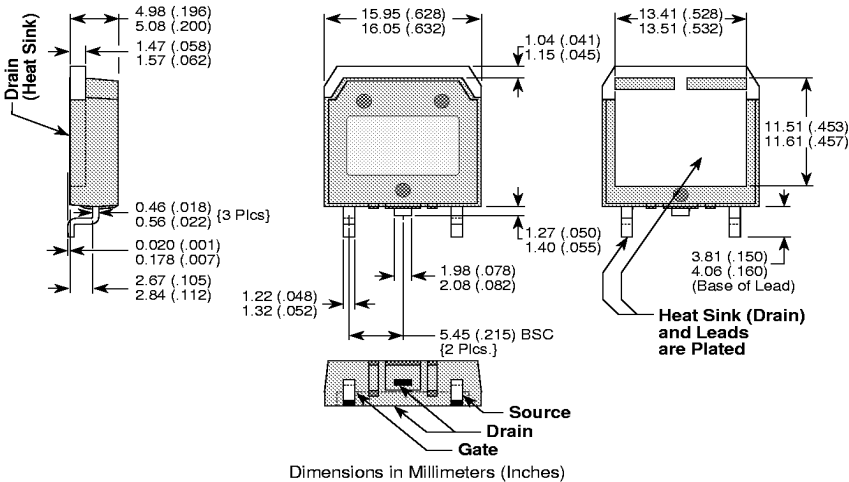
THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
R _{θJC}	Junction to Case			0.50	°C/W
R _{θJA}	Junction to Ambient			40	

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Pulse Test: Pulse width < 380 μS, Duty Cycle < 2%
- ③ See MIL-STD-750 Method 3471
- ④ Starting T_J = +25°C, L = 7.5mH, R_G = 25Ω, Peak I_L = 16A

APT Reserves the right to change, without notice, the specifications and information contained herein.

D³PAK Package Outline



050-5537 Rev A